Features

- **Low-voltage and Standard-voltage Operation**
  - **1.8 (V_{CC} = 1.8V to 5.5V)**
- **Internally Organized 256 x 8 (2K)**
- **Two-wire Serial Interface**
- **Schmitt Trigger, Filtered Inputs for Noise Suppression**
- **Bidirectional Data Transfer Protocol**
- **1 MHz (5V), 400 kHz (1.8V, 2.5V, 2.7V) Compatibility**
- **Write Protect Pin for Hardware Data Protection**
- **8-byte Page (2K) Write Modes**
- **Partial Page Writes Allowed**
- **Self-timed Write Cycle (5 ms max)**
- **High-reliability**
  - **Endurance: 1 Million Write Cycles**
  - **Data Retention: 100 Years**
- **8-lead PDIP, 8-lead JEDEC SOIC, 8-lead Ultra Thin Mini-MAP (MLP 2x3), 5-lead SOT23, 8-lead TSSOP and 8-ball dBGA2 Packages**
- **Lead-free/Halogen-free**
- **Available in Automotive**
- **Die Sales: Wafer Form and Tape and Reel**

Description

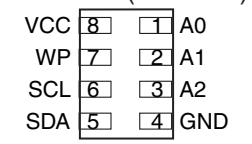
The AT24C02B provides 2048 bits of serial electrically erasable and programmable read-only memory (EEPROM) organized as 256 words of 8 bits each. The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operation are essential. The AT24C02B is available in space-saving 8-lead PDIP, 8-lead JEDEC SOIC, 8-lead Ultra Thin Mini-MAP (MLP 2x3), 5-lead SOT23, 8-lead TSSOP, and 8-ball dBGA2 packages and is accessed via a Two-wire serial interface. In addition, the AT24C02B is available in 1.8V (1.8V to 5.5V) version.

Table 0-1. Pin Configuration

Pin Name	Function
A0 - A2	Address Inputs
SDA	Serial Data
SCL	Serial Clock Input
WP	Write Protect
GND	Ground
VCC	Power Supply

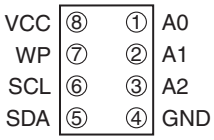
Note: For use of 5-lead SOT23, the software A2, A1, and A0 bits in the device address word must be set to zero to properly communicate.

8-lead Ultra-Thin Mini-MAP (MLP 2x3)



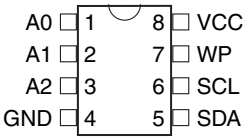
Bottom View

8-ball dBGA2

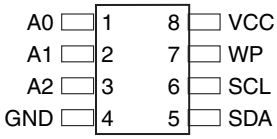


Bottom View

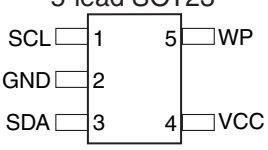
8-lead TSSOP



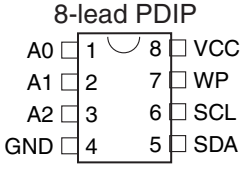
8-lead SOIC



5-lead SOT23



8-lead PDIP



Two-wire Serial EEPROM

2K (256 x 8)

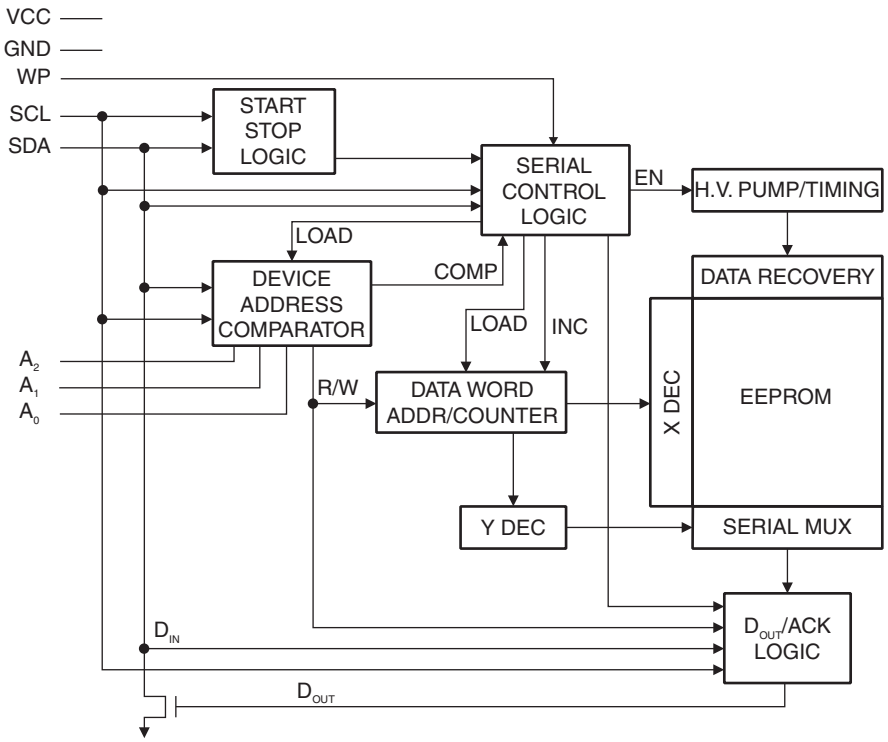
AT24C02B

Absolute Maximum Ratings

Operating Temperature	–55°C to +125°C
Storage Temperature	–65°C to +150°C
Voltage on Any Pin with Respect to Ground	–1.0V to +7.0V
Maximum Operating Voltage	6.25V
DC Output Current	5.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 0-1. Block Diagram



1. Pin Description

SERIAL CLOCK (SCL): The SCL input is used to positive edge clock data into each EEPROM device and negative edge clock data out of each device.

SERIAL DATA (SDA): The SDA pin is bidirectional for serial data transfer. This pin is open-drain driven and may be wire-ORed with any number of other open-drain or open-collector devices.

DEVICE/PAGE ADDRESSES (A2, A1, A0): The A2, A1 and A0 pins are device address inputs that are hard wired for the AT24C02B. As many as eight 2K devices may be addressed on a single bus system (device addressing is discussed in detail under the Device Addressing section).

WRITE PROTECT (WP): The AT24C02B has a write protect pin that provides hardware data protection. The write protect pin allows normal read/write operations when connected to ground

Table 2-1. Pin Capacitance[1]

Applicable over recommended operating range from T_A = 25°C, f = 1.0 MHz, V_{CC} = +1.8V

Symbol	Test Condition	Max	Units	Conditions
$C_{I/O}$	Input/Output Capacitance (SDA)	8	pF	$V_{I/O}$ = 0V
C_{IN}	Input Capacitance (A_0, A_1, A_2, SCL)	6	pF	V_{IN} = 0V

Note: 1. This parameter is characterized and is not 100% tested.

Table 2-2. DC Characteristics

Applicable over recommended operating range from: T_{AI} = –40°C to +85°C, V_{CC} = +1.8V to +5.5V, V_{CC} = +1.8V to +5.5V (unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{CC1}	Supply Voltage		1.8		5.5	V
V_{CC2}	Supply Voltage		2.5		5.5	V
V_{CC3}	Supply Voltage		2.7		5.5	V
V_{CC4}	Supply Voltage		4.5		5.5	V
I_{CC}	Supply Current V_{CC} = 5.0V	READ at 100 kHz		0.4	1.0	mA
I_{CC}	Supply Current V_{CC} = 5.0V	WRITE at 100 kHz		2.0	3.0	mA
I_{SB1}	Standby Current V_{CC} = 1.8V	V_{IN} = V_{CC} or V_{SS}		0.6	3.0	µA
I_{SB2}	Standby Current V_{CC} = 2.5V	V_{IN} = V_{CC} or V_{SS}		1.4	4.0	µA
I_{SB3}	Standby Current V_{CC} = 2.7V	V_{IN} = V_{CC} or V_{SS}		1.6	4.0	µA
I_{SB4}	Standby Current V_{CC} = 5.0V	V_{IN} = V_{CC} or V_{SS}		8.0	18.0	µA
I_{LI}	Input Leakage Current	V_{IN} = V_{CC} or V_{SS}		0.10	3.0	µA
I_{LO}	Output Leakage Current	V_{OUT} = V_{CC} or V_{SS}		0.05	3.0	µA
V_{IL}	Input Low Level[1]		–0.6		V_{CC} x 0.3	V
V_{IH}	Input High Level[1]		V_{CC} x 0.7		V_{CC} + 0.5	V
V_{OL2}	Output Low Level V_{CC} = 3.0V	I_{OL} = 2.1 mA			0.4	V
V_{OL1}	Output Low Level V_{CC} = 1.8V	I_{OL} = 0.15 mA			0.2	V

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested.

Table 2-3. AC Characteristics

Applicable over recommended operating range from T_{AI} = –40°C to +85°C, V_{CC} = +1.8V to +5.5V, CL = 1 TTL Gate and 100 pF (unless otherwise noted)

		1.8, 2.5, 2.7		5.0-volt		
Symbol	Parameter	Min	Max	Min	Max	Units
f_{SCL}	Clock Frequency, SCL		400		1000	kHz
t_{LOW}	Clock Pulse Width Low	1.2		0.4		µs
t_{HIGH}	Clock Pulse Width High	0.6		0.4		µs
t_I	Noise Suppression Time		50		40	ns
t_{AA}	Clock Low to Data Out Valid	0.1	0.9	0.05	0.55	µs

Table 2-3. AC Characteristics

Applicable over recommended operating range from T_{AI} = –40°C to +85°C, V_{CC} = +1.8V to +5.5V, CL = 1 TTL Gate and 100 pF (unless otherwise noted)

Symbol	Parameter	1.8, 2.5, 2.7		5.0-volt		Units
		Min	Max	Min	Max	
t_{BUF}	Time the bus must be free before a new transmission can start	1.2		0.5		µs
$t_{HD.STA}$	Start Hold Time	0.6		0.25		µs
$t_{SU.STA}$	Start Setup Time	0.6		0.25		µs
$t_{HD.DAT}$	Data In Hold Time	0		0		µs
$t_{SU.DAT}$	Data In Setup Time	100		100		ns
t_R	Inputs Rise Time(1)		0.3		0.3	µs
t_F	Inputs Fall Time(1)		300		100	ns
$t_{SU.STO}$	Stop Setup Time	0.6		.25		µs
t_{DH}	Data Out Hold Time	50		50		ns
t_{WR}	Write Cycle Time		5		5	ms
Endurance(1)	5.0V, 25°C, Byte Mode	1 Million				Write Cycles

Note: 1. This parameter is ensured by characterization only.

AT24C02B Ordering Information

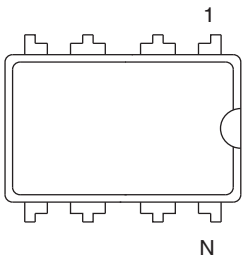
Ordering Code	Voltage	Package	Operation Range
AT24C02B-PU (Bulk form only)	1.8	8P3	Lead-free/Halogen-free/ Industrial Temperature (–40°C to 85°C)
AT24C02BN-SH-B[1] (NiPdAu Lead Finish)	1.8	8S1	
AT24C02BN-SH-T[2] (NiPdAu Lead Finish)	1.8	8S1	
AT24C02B-TH-B[1] (NiPdAu Lead Finish)	1.8	8A2	
AT24C02B-TH-T[2] (NiPdAu Lead Finish)	1.8	8A2	
AT24C02BY6-YH-T[2] (NiPdAu Lead Finish)	1.8	8Y6	
AT24C02B-TSU-T[2]	1.8	5TS1	
AT24C02BU3-UU-T[2]	1.8	8U3-1	
AT24C02B-W-11[3]	1.8	Die Sale	Industrial Temperature (–40°C to 85°C)

Notes: 1. "-B" denotes bulk.
2. "-T" denotes tape and reel. SOIC = 4K per reel. TSSOP, Ultra Thin Mini-MAP, SOT23, and dBGA2 = 5K per reel.
3. Available in tape and reel and wafer form; order as SL788 for inkless wafer form. Please contact Serial Interface Marketing.

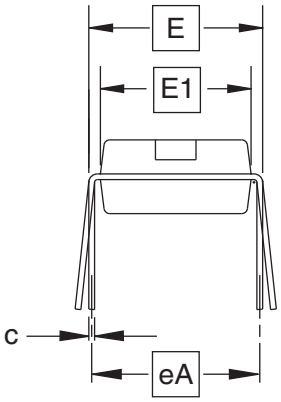
Package Type	
8P3	8-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
8S1	8-lead, 0.150" Wide, Plastic Gull Wing Small Outline (JEDEC SOIC)
8A2	8-lead, 4.4 mm Body, Plastic Thin Shrink Small Outline Package (TSSOP)
8Y6	8-lead, 2.00 mm x 3.00 mm Body, 0.50 mm Pitch, Ultra Thin Mini-MAP, Dual No Lead Package (DFN), (MLP 2x3 mm)
5TS1	5-lead, 2.90 mm x 1.60 mm Body, Plastic Thin Shrink Small Outline Package (SOT23)
8U3-1	8-ball, die Ball Grid Array Package (dBGA2)
Options	
–1.8	Low-voltage (1.8V to 5.5V)

10. Packaging Information

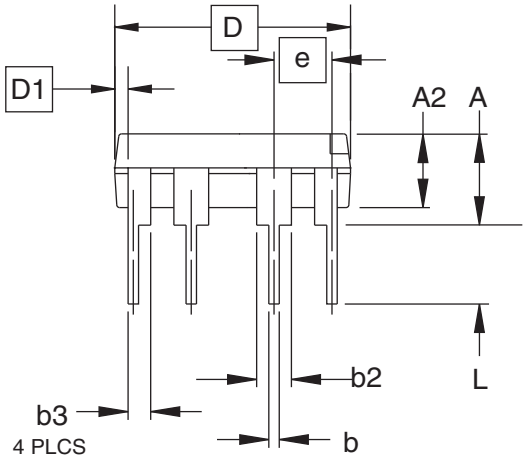
8P3 – PDIP



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure = inches)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	0.210	2
A2	0.115	0.130	0.195	
b	0.014	0.018	0.022	5
b2	0.045	0.060	0.070	6
b3	0.030	0.039	0.045	6
c	0.008	0.010	0.014	
D	0.355	0.365	0.400	3
D1	0.005	–	–	3
E	0.300	0.310	0.325	4
E1	0.240	0.250	0.280	3
e	0.100 BSC			
eA	0.300 BSC			4
L	0.115	0.130	0.150	2

Notes:
1. This drawing is for general information only; refer to JEDEC Drawing MS-001, Variation BA, for additional information.
2. Dimensions A and L are measured with the package seated in JEDEC seating plane Gauge GS-3.
3. D, D1 and E1 dimensions do not include mold Flash or protrusions. Mold Flash or protrusions shall not exceed 0.010 inch.
4. E and eA measured with the leads constrained to be perpendicular to datum.
5. Pointed or rounded lead tips are preferred to ease insertion.
6. b2 and b3 maximum dimensions do not include Dambar protrusions. Dambar protrusions shall not exceed 0.010 (0.25 mm).

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**8P3**, 8-lead, 0.300" Wide Body, Plastic Dual In-line Package (PDIP)	8P3	B